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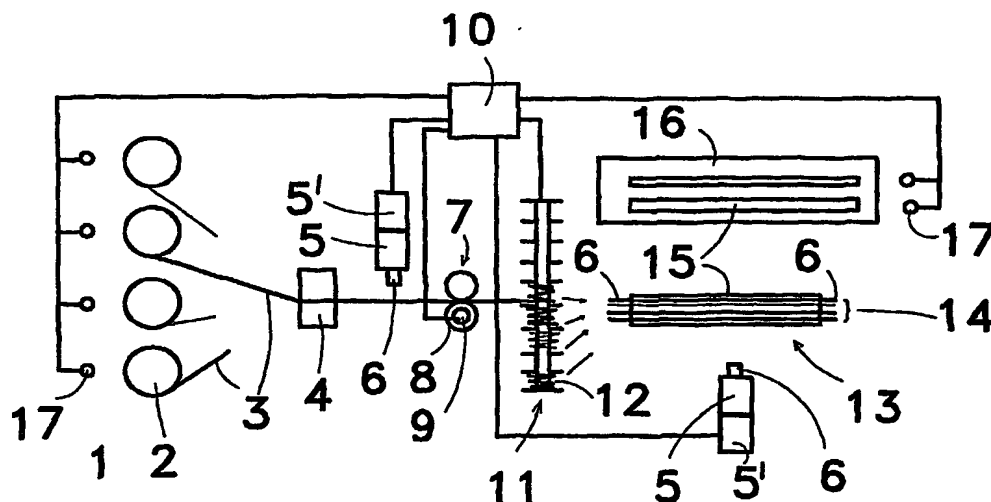
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(54) Title: WIRE HARNESS MANUFACTURING APPARATUS AND METHOD



(57) **Abstract:** A device and a method for manufacturing of bundles of wires fixed in terminal boards for building wiring allows manufacturing of bundles of wires for individual sections from one to another junction point, so that the length and sheathing of each bundle correspond to the in situ status, whereby individual wires would be labelled in a way to allow a fitter to connect wires, the ends of which will be previously stripped off and prepared for being connected to other electric elements on junction points only on the basis of labels on wires and other electric elements, without fitter's knowledge of a wiring diagram, whereby after the completion of the input of data the device of the invention automatically performs a list of circuitry elements, a wiring diagram and a circuitry plan for instance in a ground plan of an object, whereby the device of the invention also allows new methods of wiring manufacturing.